

**HPC/AI Server - 6th Gen** Intel® Xeon® - 8U DP

**NVIDIA HGX™ B300** 







Start customizing your GS7 | G894-SD3-AAX7 today!



- 8 x 800 Gb/s OSFP InfiniBand XDR /
- Dual 400 Gb/s Ethernet GPU networking ports
- via onboard NVIDIA ConnectX®-8 SuperNIC™
- 1.8TB/s GPU-to-GPU bandwidth with NVIDIA NVLink™ and NVSwitch™
- Dual Intel® Xeon® 6700/6500-Series Processors
- 8-Channel DDR5 RDIMM / MRDIMM, 32 x DIMMs
- **Dual ROM Architecture**
- Compatible with NVIDIA® BlueField®-3 DPUs
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen5 x4 and x2 interface
- 8 x 2.5" Gen5 NVMe hot-swap bays
- 4 x FHHL PCIe Gen5 x16 slots
- 12 x 3000W 80 PLUS Titanium redundant power supplies

### **About Hyperscalers**





**Free Of Proprietary Hardware Lock-Ins** 



**US Stock** 



Full US





Metro



## **Boosting Individual Applications with On-Point Features**

Intel® Xeon® 6 is a new generation of processors that has tailored its CPU lineup to target all uses cases such as Cloud Computing, AI, Analytics, and Edge & IOT. Whether it's high compute density that is dependent on core count and power efficiency or AI/HPC applications that heavily rely on strong singlecore performance, this new platform covers them all with its Performance cores (P-cores) and Efficient-cores (E-cores). Along with flexible I/O options, integrated accelerators, and support for CXL 2.0 devices, Intel Xeon 6 fulfills customer needs across the broadest range of data center workloads, segments, and deployment models.















# **GS7**|**G894-SD3-AAX7** Specifications

Processor	CPU: Intel® Xeon® 6 processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors	Video	Integrated in ASPEED® AST2600 - 1 x VGA port
	Dual processor, TDP Support: up to 350W	Storage	Front bot owen
Form Factor	8U		Front hot-swap: 8 x 2.5" Gen5 NVMe
			- (NVMe from PEX89072)
Dimensions	W x H x D (mm): 447 x 351 x 923		Internal M.2:
 Motherboard	MSB4-PE2		1 x M.2 (2280/22110), PCIe Gen5 x4, from CPU_1
Socket	2 x LGA 4710 Socket E2		1 x M.2 (2280/22110), PCIe Gen5 x2, from CPU $_{\rm L}$ 1
Chipset	System on Chip	Fans	Motherboard: 2 x 60x60x56mm / 4 x 60x60x76mm
Memory	32 x DIMM slots Support DDR5 RDIMM/MRDIMM [1] 8-Channel memory per processor RDIMM: Up to 6400 MT/s (1DPC), 5200 MT/s (2DPC) MRDIMM: Up to 8000 MT/s [1] MRDIMMs are only supported with Intel® Xeon® 6 Processors with P-cores and in a 1DPC configuration.		OSFP ports: 4 x 40x40x56mm  PCIe slots: 2 x 80x80x56mm  GPU tray: 15 x 80x80x80mm
		Rear I/O	8 x OSFP ports
			MLAN board - CDB66:
			1 x MLAN port
Modular GPU	NVIDIA HGX™ B300 with 8 x SXM GPUs PCIe Expansion Slot 4 x FHHL x16 (Gen5 x16), from PEX89072	Security Module	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM012 Power Supply[#1]
Front I/O	I/O board - CFPG440:		12 x 3000W 80 PLUS Titanium redundant power supplies [1]
	2 x USB 3.2 Gen1 ports (Type-A) 1 x VGA port 2 x RJ45 ports 1 x MLAN port (default) 1 x Power button with LED 1 x ID button with LED 1 x NMI button 1 x Reset button	Operating Properties	Operating temperature: 10°C to 30°C Operating humidity: 8% to 80% (non- condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20% to 95%
	1 x Storage activity LED		(non-condensing)
	1 x System status LED	ТРМ	TPM 2.0 SPI module (optional)

Authorised Hyperscalers Partner



# **About Hyperscalers**

Hyperscalers is the world's first open Original Equipment Manufacturer offering proprietary-free alterative to traditional Tier 1 OEM vendors.

Hereto to solve Information technology's complexity, Hyperscalers developed the IP Appliance Design Process. Which is basically a process along with a utility, being the Appliance Optimizer Utility, which together, assists service providers 'productize' delivery of their Digital-IP.

#### **Technology Partners**















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